

## T2035H, T2050H

## High temperature 20 A Snubberless™ Triacs

#### **Features**

- Medium current Triac
- 150 °C max. T<sub>i</sub> turn-off commutation
- Low thermal resistance with clip bonding
- Very high 3 quadrant commutation capability
- Packages are RoHS (2002/95/EC) compliant
- UL certified (ref. file E81734)

#### **Applications**

Especially designed to operate in high power density or universal motor applications such as vacuum cleaner and washing machine drum motor.

#### **Description**

Available in through-hole and surface mount packages, the T2035H and T2050H Triac series are suitable for general purpose mains power AC switching.

These 20 A Triacs provide a very high switching capability up to junction temperatures of 150 °C.

The heatsink can be reduced, compared to traditional Triacs, according to the high performance at given junction temperatures.

By using an internal ceramic pad, the T20xxH-6l provides voltage insulation (rated at 2500 V rms).

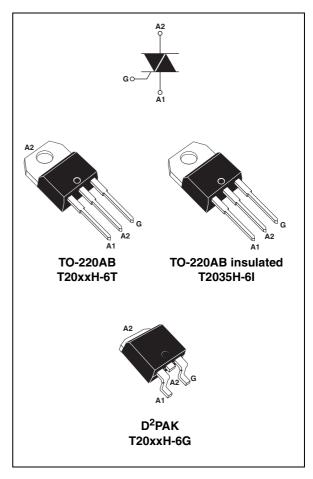


Table 1. Device summary

Symbol	Value	Unit
I <sub>T(RMS)</sub>	20	Α
V <sub>DRM</sub> /V <sub>RRM</sub>	600	V
I <sub>GT</sub>	35 or 50	mA

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Characteristics T2035H, T2050H

## 1 Characteristics

Table 2. Absolute maximum ratings

Symbol	Parame	Value	Unit			
	On state rms current (full sine ways)	TO-220AB, D <sup>2</sup> PAK	T <sub>c</sub> = 128 °C	20	Α	
I <sub>T(RMS)</sub>	On-state rms current (full sine wave)	TO-220AB insulated	T <sub>c</sub> = 108 °C			
	Non repetitive surge peak on-state	F = 50 Hz	t = 20 ms	200	۸	
I <sub>TSM</sub>	current (full cycle, T <sub>j</sub> initial = 25 °C)	F = 60 Hz	t = 16.7 ms	210	Α	
l <sup>2</sup> t	$l^2t$ Value for fusing $t_p = 10 \text{ ms}$		265	A <sup>2</sup> s		
dl/dt	Critical rate of rise of on-state current $I_G$ = 2 x $I_{GT}$ , $t_r \le 100$ ns $T_j = 150$ °		T <sub>j</sub> = 150 °C	50	A/μs	
V <sub>DSM</sub> /V <sub>RSM</sub>	Non repetitive surge peak off-state voltage	t <sub>p</sub> = 10 ms	T <sub>j</sub> = 25 °C	V <sub>DRM</sub> /V <sub>RRM</sub> + 100	٧	
I <sub>GM</sub>	Peak gate current $t_p = 20 \ \mu s$ $T_j = 150 \ ^{\circ}C$		T <sub>j</sub> = 150 °C	4	Α	
P <sub>G(AV)</sub>	Average gate power dissipation	1	W			
T <sub>stg</sub> T <sub>j</sub>	Storage junction temperature range Operating junction temperature range			- 40 to + 150 - 40 to + 150	°C	

Table 3. Electrical characteristics ( $T_i = 25$  °C, unless otherwise specified)

Symbol	Test conditions	Quadrant	Value			Unit	
Symbol	rest conditions	Quadrant		T2035H	T2050H	Oilit	
I <sub>GT</sub> <sup>(1)</sup>	$V_D = 12 \text{ V}, R_1 = 33 \Omega$	1 - 11 - 111	MAX.	35	50	mA	
V <sub>GT</sub>	VD = 12 V, 11[ = 00 \$2	1 - 11 - 111	MAX.	1	.0	V	
$V_{GD}$	$V_D = V_{DRM}$ , $R_L = 3.3 \text{ k}\Omega$		MIN.	0.15		V	
I <sub>H</sub> <sup>(2)</sup>	I <sub>T</sub> = 500 mA		MAX.	35	75	mA	
IL	I <sub>G</sub> = 1.2 I <sub>GT</sub>	1 - 111	MAX.	50	90	mA	
'L	IG - 1.2 IGT	II	IVIAA.	80	110	111/4	
dV/dt (2)	V <sub>D</sub> = 67% V <sub>DRM,</sub> gate open, T <sub>j</sub> = 150 °C			1000	1500	V/µs	
(dl/dt) <sub>c</sub> (2)	Without snubber, T <sub>j</sub> = 150 °C			27	36	A/ms	

<sup>1.</sup> minimum  $I_{\mbox{\scriptsize GT}}$  is guaranteed at 20% of  $I_{\mbox{\scriptsize GT}}$  max.

<sup>2.</sup> for both polarities of A2 referenced to A1.

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Table 4. Static characteristics

Symbol	Test conditions	Value	Unit		
V <sub>T</sub> <sup>(1)</sup>	I <sub>TM</sub> = 28 A, t <sub>p</sub> = 380 μs	T <sub>j</sub> = 25 °C	MAX.	1.5	V
V <sub>t0</sub> (1)	Threshold voltage	T <sub>j</sub> = 150 °C	MAX.	0.80	V
R <sub>d</sub> <sup>(1)</sup>	Dynamic resistance	T <sub>j</sub> = 150 °C	MAX.	19	mΩ
	V - V	T <sub>j</sub> = 25 °C	MAX.	5	μΑ
I <sub>DRM</sub>	$V_{DRM} = V_{RRM}$	T <sub>j</sub> = 150 °C	MAX.	6.2	
I <sub>RRM</sub> <sup>(2)</sup>	V <sub>D</sub> /V <sub>R</sub> = 400 V (at peak mains voltage)	T <sub>j</sub> = 150 °C	MAX.	5.0	mA
	V <sub>D</sub> /V <sub>R</sub> = 200 V (at peak mains voltage)	T <sub>j</sub> = 150 °C	MAX.	4.0	

<sup>1.</sup> for both polarities of A2 referenced to A1.

Table 5. Thermal resistance

Symbol	Par	Value	Unit	
В	lunction to cope (AC)	TO-220AB, D <sup>2</sup> PAK	1	
R <sub>th(j-c)</sub>	Junction to case (AC)	TO-220AB Ins	1.9	°C/W
В	Junction to ambient	TO-220AB, TO-220AB insulated	60	C/VV
R <sub>th(j-a)</sub>	$S = 1 \text{ cm}^2$	D <sup>2</sup> PAK	45	

<sup>2.</sup>  $t_p = 380 \mu s$ .

Characteristics T2035H, T2050H

Figure 1. Maximum power dissipation versus Figure 2. On-state rms current versus case on-state rms current temperature

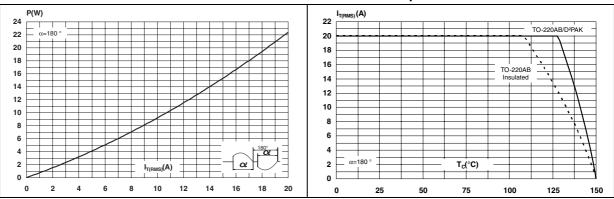


Figure 3. On-state rms current versus ambient temperature

Figure 4. Variation of thermal impedance versus pulse duration

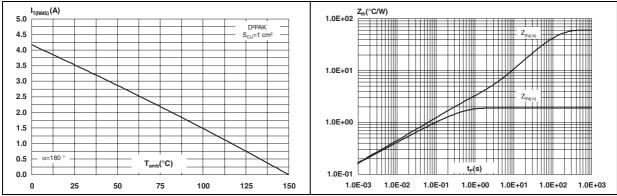
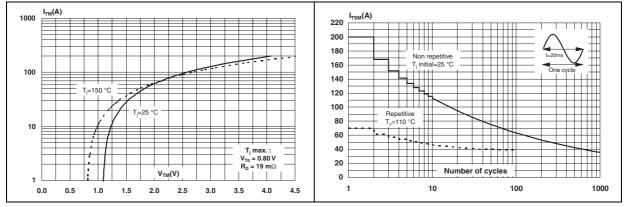


Figure 5. On-state characteristics (maximum values)

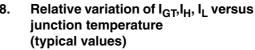
Figure 6. Surge peak on-state current versus number of cycles

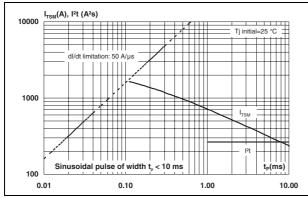


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T2035H, T2050H Characteristics

Figure 7. Non-repetitive surge peak on-state Figure 8. current and corresponding values of I<sup>2</sup>t





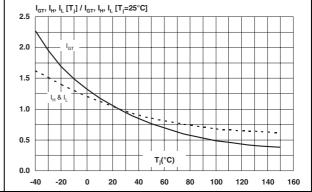
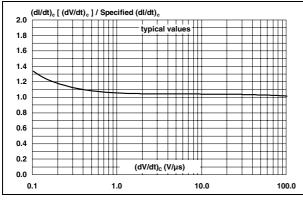


Figure 9. Relative variation of critical rate of Figure 10. decrease of main current (dl/dt)<sub>c</sub> versus reapplied (dV/dt)<sub>c</sub>

Figure 10. Relative variation of critical rate of decrease of main current versus junction temperature



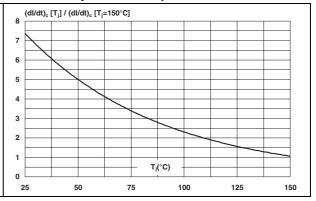
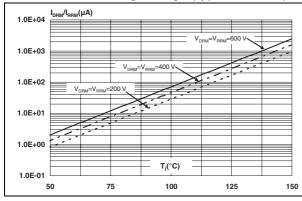


Figure 11. Leakage current versus junction temperature for different values of blocking voltage (typical values)

Figure 12. Acceptable repetitive peak off-state voltage versus case to ambient thermal resistance



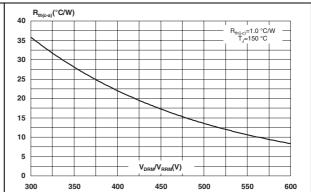
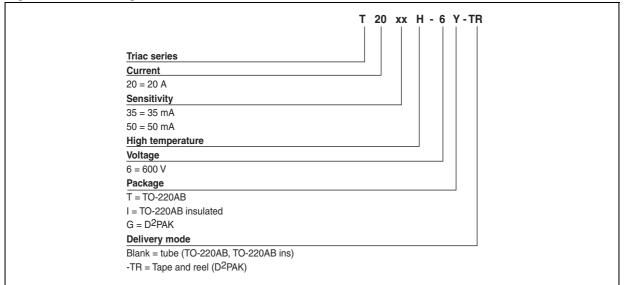


Figure 13. Thermal resistance junction to ambient versus copper surface under tab

# 2 Ordering information

Figure 14. Ordering information



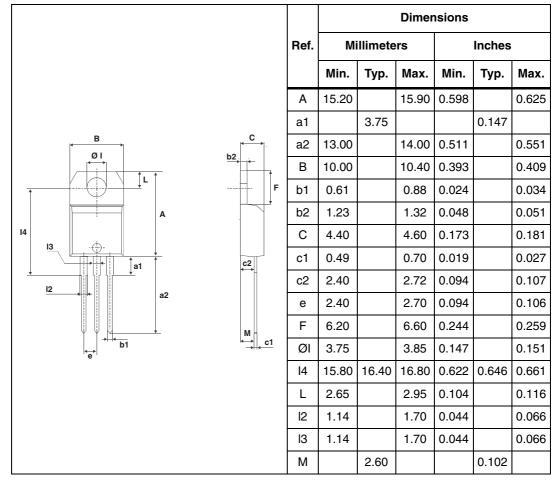
T2035H, T2050H Package information

### 3 Package information

- Epoxy meets UL94, V0
- Recommended torque 0.4 to 0.6 N⋅m

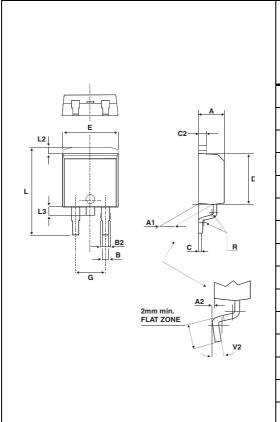
In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: <a href="https://www.st.com">www.st.com</a>. ECOPACK<sup>®</sup> is an ST trademark.

Table 6. TO-220AB and TO-220AB insulated dimensions



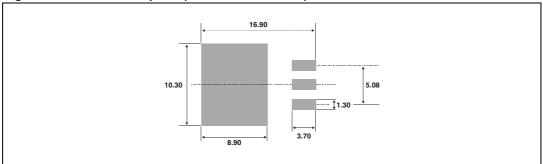
Package information T2035H, T2050H

Table 7. D<sup>2</sup>PAK dimensions



	Dimensions					
Ref.	Mi	Millimete		Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	4.30		4.60	0.169		0.181
A1	2.49		2.69	0.098		0.106
A2	0.03		0.23	0.001		0.009
В	0.70		0.93	0.027		0.037
B2	1.25	1.40		0.048	0.055	
С	0.45		0.60	0.017		0.024
C2	1.21		1.36	0.047		0.054
D	8.95		9.35	0.352		0.368
Е	10.00		10.28	0.393		0.405
G	4.88		5.28	0.192		0.208
L	15.00		15.85	0.590		0.624
L2	1.27		1.40	0.050		0.055
L3	1.40		1.75	0.055		0.069
R	0.40				0.016	
V2	0°		8°	0°		8°

Figure 15. D<sup>2</sup>PAK footprint (dimensions in mm)



# 4 Ordering information

Table 8. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
T20xxH-6T	T20xxH 6T	TO-220AB	2.3 g	50	Tube
T20xxH-6I	T20xxH 6T	TO-220AB insulated	2.3 g	50	Tube
T20xxH-6G-TR	T20xxH 6G	D <sup>2</sup> PAK	1.5 g	1000	Tape and reel

# 5 Revision history

Table 9. Document revision history

Date	Revision	Changes
31-May-2007	1	First issue.
15-Nov-2007	2	Added TO-220AB Ins and D <sup>2</sup> PAK packages. Reformatted to current standards.
08-Aug-2011	3	Updated: Features and Description. Removed order code T20xxH-6G from Figure 14 and Table 8.

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